

SERIES 58 BIGGER. FASTER. SMARTER.



ENGLISH

58
SERIES

BONDING THE STARS

FVS
BONDTEC

SERIES 58

The Production Machine

YOU NEED: 1,000 TO 100,000 WIRE BONDS PER DAY

- >> In-house production to protect your technology and to provide short Time-to-Market
- >> Wire bonding for small to medium production volumes; high quality requirements
- >> High Mix / Medium Volume; frequent product changes at medium lot sizes



THE SOLUTION: SERIES 58

58
SERIES

- >> A complete high productivity tabletop wire bonder at over 1 wire per second
- >> Unbeatable price-to-performance ratio
- >> Exchangeable bond heads for all wire bond processes
- >> Fully automatic wire bonding with manual parts feeding
- >> Store an unlimited number of bond programs
- >> Extremely adaptable bond settings, loop shapes, force and power profiles etc.
- >> Most powerful pattern recognition system on the market
- >> Innovative software



5810 – Gold-Ball Bonder



- >> Gold-ball bonding for wires from 17.5 to 50 μm using standard capillaries 16 mm to 19 mm
- >> Highly sensitive, contactless electronic touchdown sensor and digitally controlled, programmable bond force for delicate component surfaces
- >> Digital ultrasonic generator provides adjustable bond frequencies
- >> Bumping, safety bump, stitch-on-ball



5830 – Wedge-Wedge Bonder



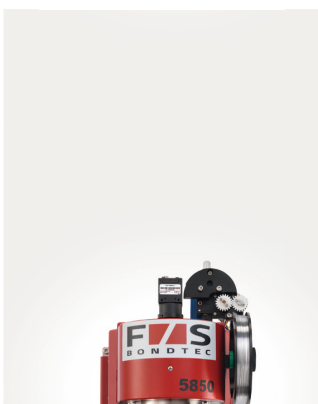
- >> Wedge-wedge bonding using 1" tools for aluminum and gold wires from 17.5 to 75 μm
- >> 45° wire guide, convertible to 30° or 60° depending on component geometry
- >> Digital ultrasonic generator provides adjustable bond frequencies
- >> Deformation Limit Control (DLC) for real-time quality check and process monitoring



5832 – Deep-Access Ribbon Bonder



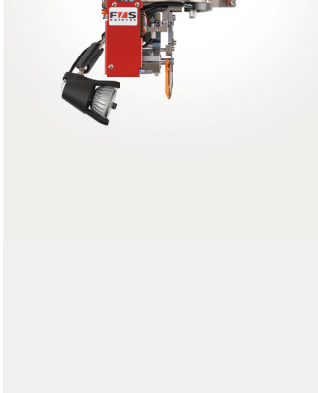
- >> Wedge-wedge bonding using 1" or 3/4" tools
- >> 90° wire guide for aluminum and gold wires from 17.5 to 75 μm
- >> Perfect for difficult and constricted bonding geometries
- >> Ideally suited for aluminum and gold ribbons



5850 – Heavy Wire Bonder



- >> Wedge-wedge bonding for aluminum and copper heavy wire from 100 up to 500 μm diameter
- >> Wedge lengths of 50 up to 70 mm even for extreme bonding requirements
- >> Stitch or chain bonds of any length
- >> Clip-on wire guide for quick exchange
- >> Deformation Limit Control (DLC) for quality control



5850 HR – Heavy Ribbon Bonder

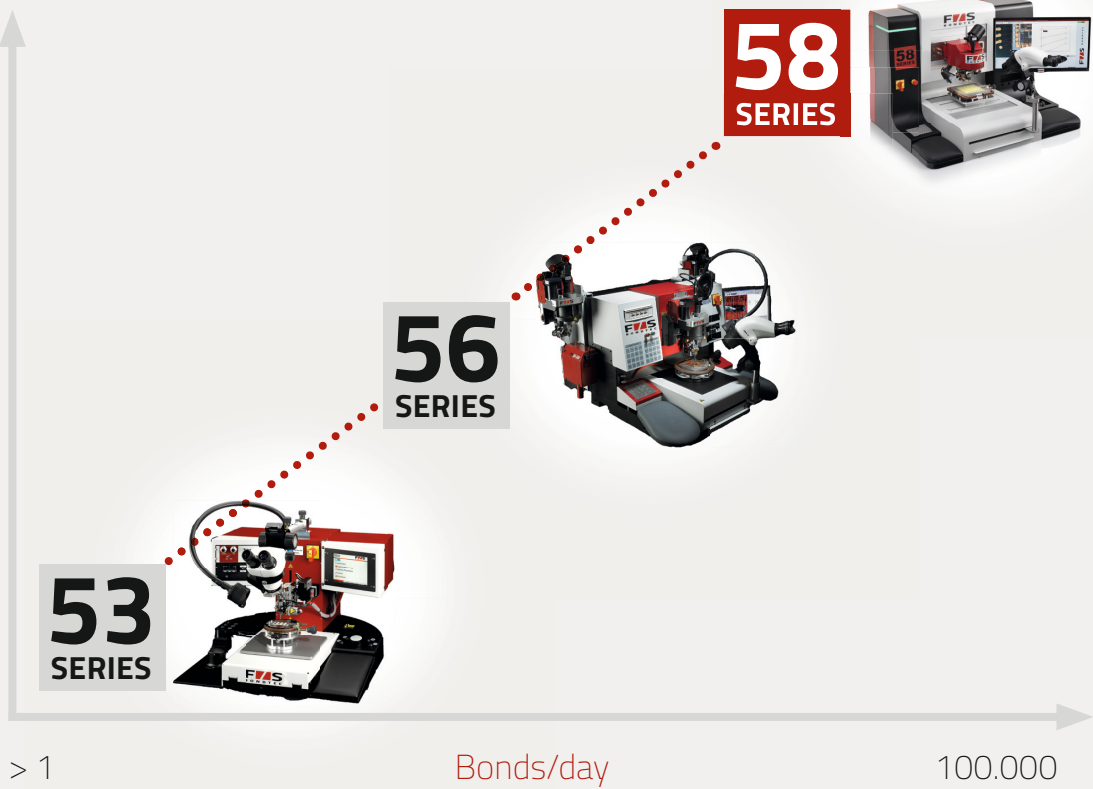


- >> Wedge-wedge bonding for heavy aluminum or copper ribbons up to 2 mm width
- >> Increased programmable bond force up to 6,000 cN, also with force and power ramps
- >> Active ribbon guide to improve loop shaping
- >> Optional: convertible from standard 5850 bond head

fully automatic

automation level

manual



TECHNOLOGY	SERIES 53	SERIES 56	SERIES 58
GOLD-BALL	5310, 53xx BDA	5610	5810
THIN WIRE WEDGE-WEDGE	5330	5630	5830
THIN WIRE DEEP ACCESS	53xx BDA	5632	5832
HEAVY WIRE	5350	5650	5850
HEAVY RIBBON	5350 HR	5650 HR	5850 HR



TEC ASSOCIATES INC.
 111 DEERWOOD ROAD SUITE #198
 SAN RAMON, CA 94583
 T: 925-831-1700
 EMAIL: SALES@TECREPS.COM



F&S BONDTEC
 Industriezeile 49a
 5280 Braunau/Inn
 Austria

ISO-9001/2008-certified

Phone: +43-7722-67052-8270
Fax: +43-7722-67052-8272
E-mail: info@fsbondtec.at

www.fsbondtec.at

BONDING THE STARS

